

**Listing of Claims:**

This listing of claims reflects all claim amendments and replaces all prior versions, and listings, of claims in the application. Material to be inserted is in **bold and underline**, and material to be deleted is in ~~strikeout~~ or (if the deletion is of five or fewer consecutive characters or would be difficult to see) in double brackets [[ ]].

Please amend claims 1, 2, 11 and 12 as indicated below.

Please add new claims 13-16.

1. (Currently Amended) An apparatus for bonding two optical disc substrates together by joining the optical disc substrates together with an adhesive and by curing the adhesive, which comprises an adhesive-supplying nozzle for supplying the adhesive onto at least one of the optical disc substrates, an electrode means placed in contact with or in the vicinity of the surface of the optical disc substrate which is opposite to the surface which faces the adhesive-supplying nozzle, and an electric power supply for generating an electric field between the electrode means and the adhesive-supplying nozzle, and a joining apparatus for joining one of the optical disc substrates, onto at least one of which the adhesive is supplied, and another one of the optical disc substrates.

2. (Currently Amended) The apparatus according to claim 1, wherein the adhesive-supplying nozzle comprises a single nozzle or two nozzles placed separated from each other by almost 180 degrees away from each other, is placed over the optical disc substrate nearly perpendicular thereto with its tip(s) pointing downward, and forms a

ring-shaped adhesive liquid film on the optical disc substrate which ~~spins~~ rotates relative to the nozzle(s).

3. (Original) The apparatus according to claim 1, wherein the adhesive-supplying nozzle comprises a plurality of nozzles placed at an approximately uniform spacing in a circular shape, is placed under the optical disc substrate nearly perpendicular thereto with their tips pointing upward, and supplies dot-shaped adhesive liquid films onto the underside of the optical disc substrate.

4. (Original) The apparatus according to claim 1, wherein the electric power supply generates an alternating-current electric field.

5. (Original) The apparatus according to claim 2, wherein the electric power supply generates an alternating-current electric field.

6. (Original) The apparatus according to claim 3, wherein the electric power supply generates an alternating-current electric field.

7. (Original) The apparatus according to claim 1, wherein the electric power supply generates a direct-current electric field.

8. (Original) The apparatus according to claim 2, wherein the electric power supply generates a direct-current electric field.

9. (Original) The apparatus according to claim 3, wherein the electric power supply generates a direct-current electric field.

10. (Original) The apparatus according to claim 1, wherein the electric power supply generates the electric field between the electrode means and the adhesive-supplying nozzle, so as to taper an end of a liquid film of the adhesive which is supplied by the adhesive-supplying nozzle toward the optical disc substrate in order to reduce an initial contact area between said end of the liquid film of the adhesive and the optical disc substrate for preventing generation of voids in said adhesive.

11. (Currently Amended) The apparatus according to claim 1, An optical disc bonding apparatus for joining two optical disc substrates together with an adhesive and forming an optical disc, the apparatus comprising: a device for forming an electric field between said two optical disc substrates, wherein  
an end of a liquid film of said adhesive which is supplied onto one of said optical disc substrates tapers, thereby making a contact area between said end of said liquid film and the other of said optical disc substrates which is opposed to said end smaller by an effect of said electric field, and generation of voids in said liquid film is prevented.

12. (Currently Amended)

The apparatus according to claim 1, An

~~optical disc bonding apparatus for joining two optical disc substrates together with an adhesive and forming an optical disc, the apparatus comprising:~~ a device for forming an electric field between said two optical disc substrates, wherein

an end of a liquid film of said adhesive which is supplied onto one of said optical disc substrates tapers, thereby making a contact area between said end of said liquid film and other liquid film of said adhesive which is supplied onto the other of said optical disc substrates and is opposed to said end smaller by an effect of said electric field, and generation of voids in said liquid film is prevented.

13. (New)

The apparatus according to claim 1, further comprising a lower support mounting one of the optical disc substrates onto at least one of which the adhesive is supplied, an upper support which is opposed to the lower support and mounts another one of the optical disc substrates, and a lifting member making the lower support move upward in order to allow a spacing between the optical disc substrates to become smaller.

14. (New)

The apparatus according to claim 1, wherein the apparatus is adapted to perform a spinning process on the optical disc substrates joined by the joining apparatus.

15. (New) The apparatus according to claim 1, wherein the adhesive-supplying nozzle is adapted to supply the adhesive onto an optical disc substrate which is being rotated.

16. (New) The apparatus according to claim 1, wherein the apparatus is configured such that, at a time when the adhesive-supplying nozzle supplies the adhesive onto the optical disc substrate, the adhesive-supplying nozzle is being rotated.